

**ON Semiconductor**<sup>®</sup>

## FGB40T65SPD-F085 650V, 40A Field Stop Trench IGBT

#### Features

- AEC-Q101 Qualified
- Low Saturation Voltage :  $V_{CE(sat)}$  = 2.0 V(Typ.) @ I<sub>C</sub> = 40 A
- 100% of the parts are dynamically tested (Note 1)
- Short Circuit Ruggedness > 5  $\mu s$  @ 25  $^{o}C$
- Maximum Junction Temperature :  $T_J = 175 \ ^{o}C$
- Fast Switching
- Tight Parameter Distribution
- · Positive Temperature Coefficient for Easy Parallel Operation
- Copacked with soft, fast recovery diode
- RoHS Compliant

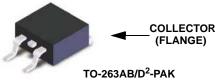


### **General Description**

Using the novel field stop 3rd generation IGBT technology, FGH40T65SPD-F085 offers the optimum performance with both low conduction loss and switching loss for a high efficiency operation in various applications, while provides 50V higher blocking voltage and rugged high current switching reliability. Meanwhile, this part also offers and advantage of outstanding performance in parallel operation.

#### Applications

- Onboard Charger
- AirCon Compressor
- PTC Heater
- Motor Drivers
- Other automotive power-train and auxiliary applications



GCE

٥C

#### **Absolute Maximum Ratings**

Symbol	Description		Ratings	Units	
V <sub>CES</sub>	Collector to Emitter Voltage		650	V	
V <sub>GES</sub>	Gate to Emitter Voltage		± 20	V	
	Transient Gate to Emitter Voltage		± 30	V	
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 25 °C	80	A	
'C	Collector Current	@ T <sub>C</sub> = 100 °C	40	A	
I <sub>CM</sub>	Pulsed Collector Current	(Note 2)	120	A	
	Diode Forward Current	@ T <sub>C</sub> = 25 °C	40	A	
I <sub>F</sub>	Diode Forward Current	@ T <sub>C</sub> = 100 °C	20	A	
I <sub>FM</sub>	Pulsed Diode Maximum Forward Curren	t (Note 2)	120	A	
D	Maximum Power Dissipation	@ T <sub>C</sub> = 25 °C	267	W	
P <sub>D</sub>	Maximum Power Dissipation	@ T <sub>C</sub> = 100 °C	134	W	
SCWT	Short Circuit Withstand Time	@ T <sub>C</sub> = 25 °C	5	μs	
TJ	Operating Junction Temperature		-55 to +175	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +175	°C	
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

Notes:

1: Vcc = 400 V, V<sub>GE</sub> = 15 V, Ic = 120 A, R<sub>G</sub> = 20  $\Omega$ , Inductive Load 2: Repetitive rating: pulse width limited by max. junction temperature

Device MarkingDeviceFGB40T65SPDFGB40T65SPD-F085TC		Package	Reel Size	Тар	e Width	Qty per Ree		
		TO-263AB/D2-PAK	-	-		800ea		
Electric	al Char	acteristics of the	<b>IGBT</b> T <sub>C</sub> = 25 °C ur	less otherwise noted				
Symbol		Parameter	Test Cor	ditions	Min.	Тур.	Max.	Units
Off Charac	cteristics							
BV <sub>CES</sub>		o Emitter Breakdown Volta	ge V <sub>GE</sub> = 0V, I <sub>C</sub> = 1n	ηA	650	-	-	V
$\frac{\Delta BV_{CES}}{\Delta T_{J}}$		re Coefficient of Breakdow	(n	$V_{GE} = 0V, I_C = 1mA$ $V_{GE} = 0V, I_C = 1mA$		0.6	-	V/ºC
I <sub>CES</sub>		Cut-Off Current	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub>	= 0V	-	-	250	μA
I <sub>GES</sub>	G-E Leaka	ige Current	$V_{GE} = V_{GES}, V_{CE}$		-	-	± 400	nA
On Charac		-				II		1
V <sub>GE(th)</sub>		hold Voltage	I <sub>C</sub> = 40mA, V <sub>CE</sub> =	V <sub>GE</sub>	4.0	5.8	7.5	V
- GE(III)				$I_{\rm C} = 40$ A, $V_{\rm GE} = 15$ V		2.0	2.4	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage		le I <sub>C</sub> = 40A, V <sub>GE</sub> = 1	$I_{C} = 40A, V_{GE} = 15V,$ $T_{C} = 175 \text{ °C}$		2.9	_	V
Dynamic C	Characterist	ics						
C <sub>ies</sub>	Input Capa	acitance		0)/	-	1520	-	pF
C <sub>oes</sub>	Output Ca	Output Capacitance		V <sub>CE</sub> = 30V, V <sub>GE</sub> = 0V, f = 1MHz		92	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance					15	-	pF
Switching	Characteris	stics						
T <sub>d(on)</sub>	Turn-On D	elay Time			-	18	-	ns
T <sub>r</sub>	Rise Time				-	26	-	ns
T <sub>d(off)</sub>	Turn-Off D	elay Time	V <sub>CC</sub> = 400V, I <sub>C</sub> =	40A,	-	35	-	ns
T <sub>f</sub>	Fall Time		R <sub>G</sub> = 6Ω, V <sub>GE</sub> = 1	5V,	-	10	-	ns
Eon	Turn-On S	witching Loss	Inductive Load, T	<sub>C</sub> = 25 °C	-	0.97	-	mJ
E <sub>off</sub>	Turn-Off S	witching Loss		F	-	0.28	-	mJ
E <sub>ts</sub>	Total Swite	hing Loss		ľ	-	1.25	-	mJ
T <sub>d(on)</sub>	Turn-On D	elay Time			-	14	-	ns
T <sub>r</sub>	Rise Time			F	-	35	-	ns
T <sub>d(off)</sub>	Turn-Off D	elay Time	V <sub>CC</sub> = 400V, I <sub>C</sub> =	40A,	-	38	-	ns
T <sub>f</sub>	Fall Time		R <sub>G</sub> = 6Ω, V <sub>GE</sub> = 1	5V,	-	13	-	ns
E <sub>on</sub>	Turn-On S	witching Loss	Inductive Load, T	<sub>C</sub> = 175 °C	-	1.61	-	mJ
E <sub>off</sub>	Turn-Off S	witching Loss		ľ	-	0.47	-	mJ
E <sub>ts</sub>	Total Swite	hing Loss		-	-	2.08	-	mJ
	1		V <sub>CC</sub> = 400V, V <sub>GE</sub>	- 451/		1		

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### Electrical Characteristics of the IGBT (Continued)

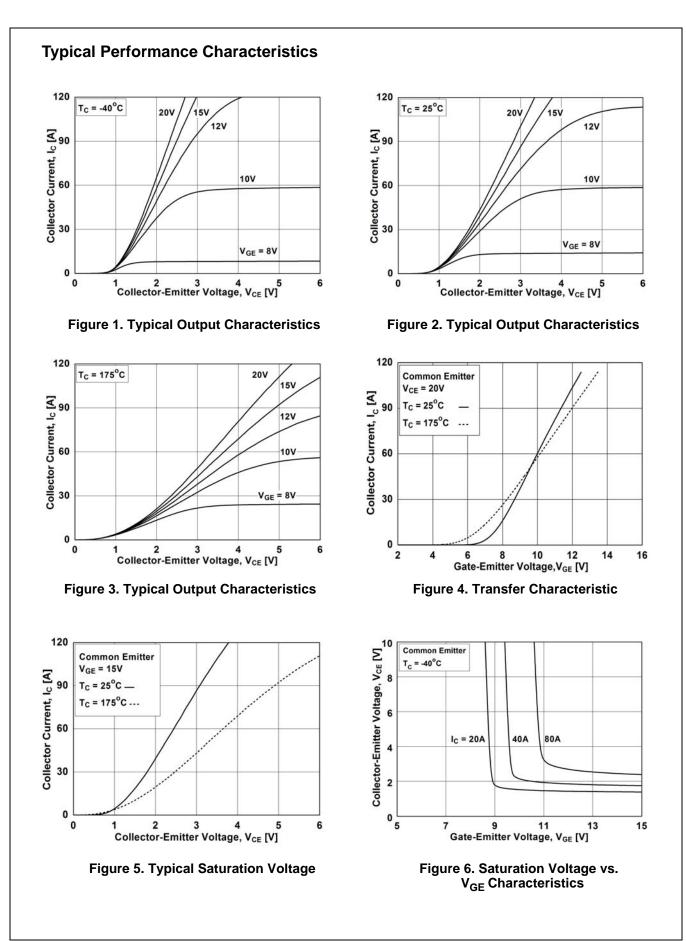
Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Units
Qg	Total Gate Charge	V <sub>CE</sub> = 400V, I <sub>C</sub> = 40A, V <sub>GE</sub> = 15V	-	36	-	nC
Q <sub>ge</sub>	Gate to Emitter Charge		-	12	-	nC
Q <sub>gc</sub>	Gate to Collector Charge		-	11	-	nC

## Electrical Characteristics of the Diode $T_C = 25$ °C unless otherwise noted

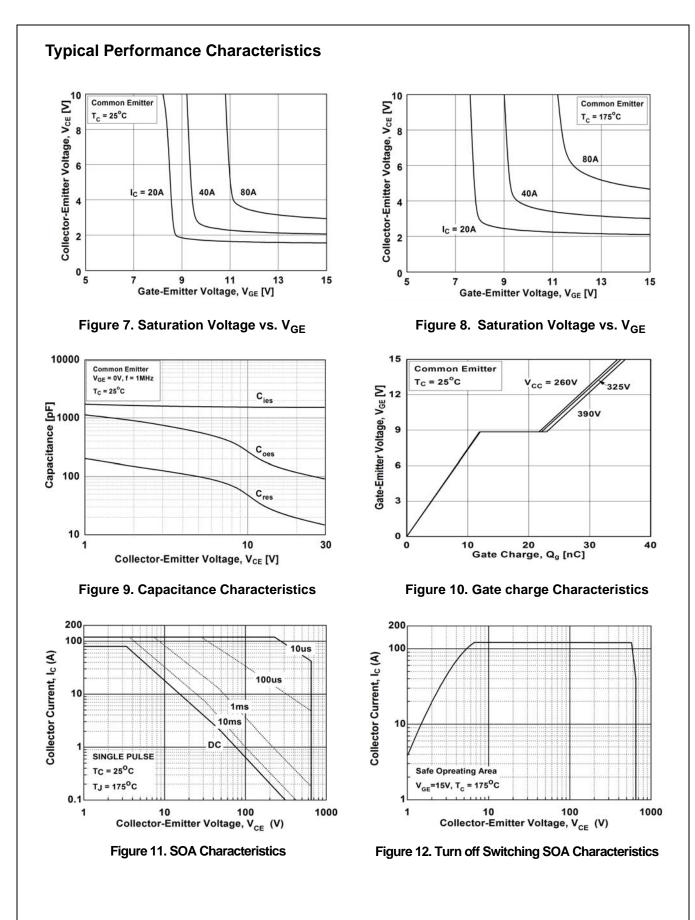
Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Units
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> = 20A	T <sub>C</sub> = 25 <sup>o</sup> C	-	2.0	2.7	V
			T <sub>C</sub> = 175 °C	-	1.8	-	
E <sub>rec</sub>	Reverse Recovery Energy	I <sub>F</sub> = 20A, dI <sub>F</sub> /dt = 200A/μs	T <sub>C</sub> = 175 °C	-	51	-	μJ
T <sub>rr</sub>	Diode Reverse Recovery Time		T <sub>C</sub> = 25 <sup>o</sup> C	-	34	-	ns
			T <sub>C</sub> = 175 <sup>o</sup> C	-	206	-	
Q <sub>rr</sub>	Diode Reverse Recovery Charge		T <sub>C</sub> = 25 °C	-	56	-	nC
			T <sub>C</sub> = 175 <sup>o</sup> C	-	731	-	

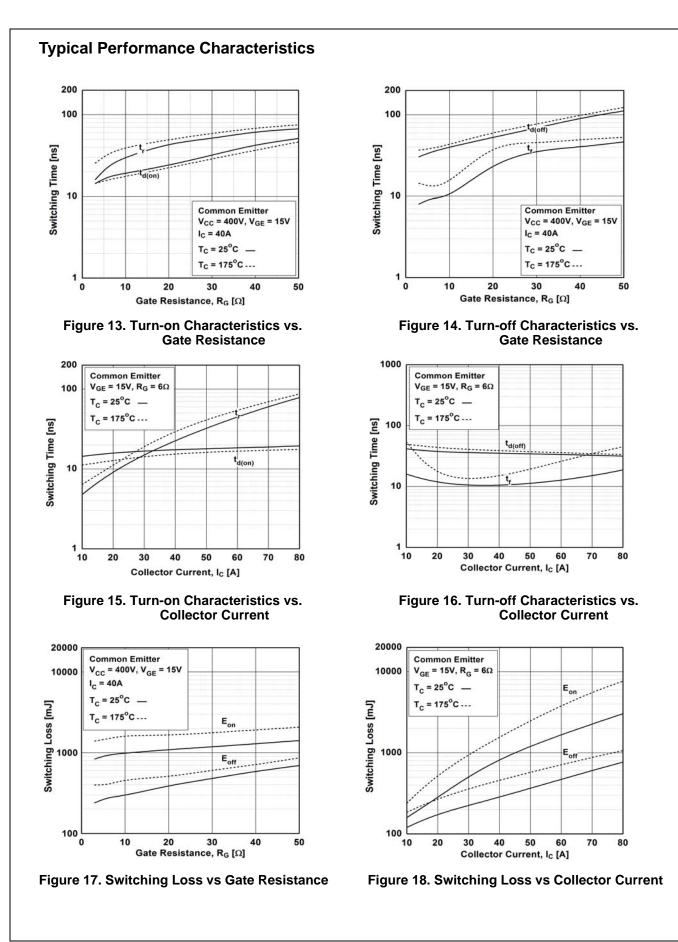
## **Thermal Characteristics**

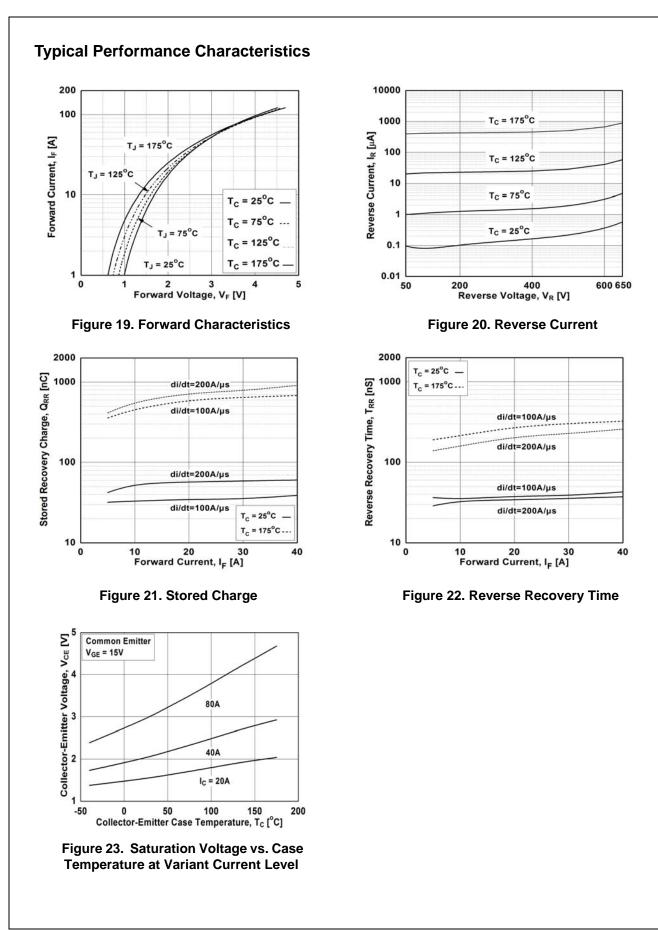
Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.56	°C/W
$R_{\theta JC}$ (Diode)	Thermal Resistance, Junction to Case	-	1.71	°C/W
$R_{ ext{ heta}JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

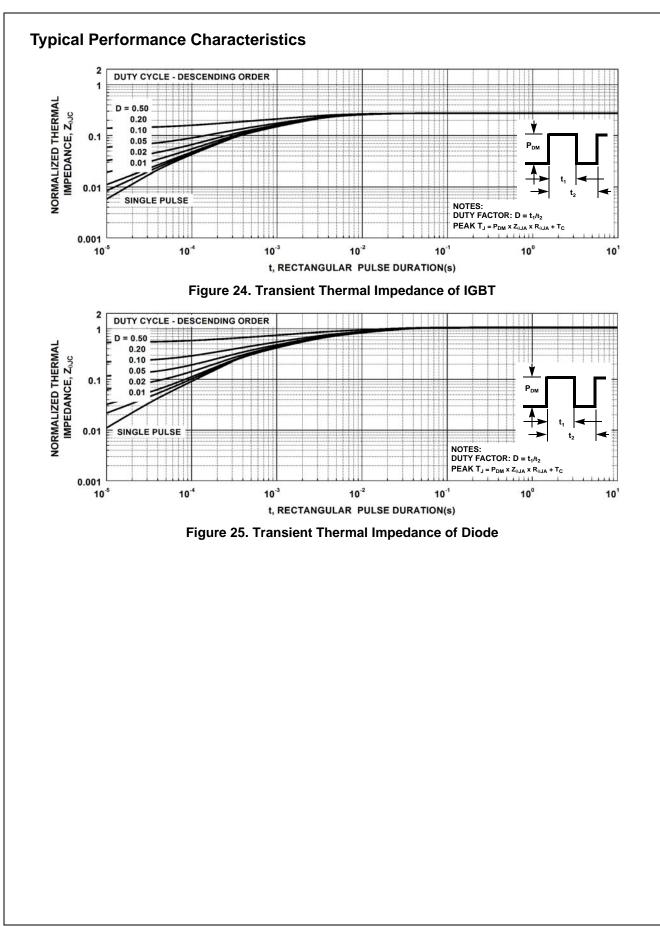


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